



Electronic Filing System (EFS) Data Electronic Patent Application Submission

USPTO Use Only

RECEIVED

JUL 27 2004

TECH CENTER 2007

EFS ID: 65085
Application ID: 09972011
Title of Invention: Method and arrangement for layout and manufacture of nonmanhattan semiconductor integrated circuit using simulated euclidean wiring
First Named Inventor: Steven Teig
Domestic/Foreign Application: Domestic Application
Filing Date: 2001-10-05
Effective Receipt Date: 2004-07-22
Submission Type: Information Disclosure Statement
Filing Type:
Confirmation number: 5250
Attorney Docket Number: SPLX.P0068
Total Fees Authorized: 180.0
Payment Category: Credit Card
Credit Card Number: *****7556
Expiration Date: 08312004
Card Holder Name: Mani Adeli
Postal Code: 94303
RAM Payment Status: RAM success
RAM User ID: EFSPROD
RAM Accounting Date: 2004-07-22
RAM Sequence Number: 1084080




Digital Certificate Holder: cn=Mani Adeli,ou=Registered Attorneys,ou=Patent and Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US
Certificate Message Digest: e1c53dc2f093450d3e2c7e3f4712fde5283cb03a

**TRANSMITTAL**

Electronic Version v1.1
Stylesheet Version v1.1.0

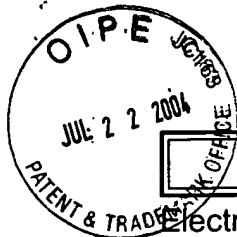
JUL 27 2004

TECH CENTER 2004

Title of Invention	Method and arrangement for layout and manufacture of nonmanhattan semiconductor integrated circuit using simulated euclidean wiring															
<p>Application Number: 09/972011 </p> <p>Date: 2001-10-05</p> <p>First Named Applicant: Steven Teig</p> <p>Confirmation Number: 5250</p> <p>Attorney Docket Number: SPLX.P0068</p>																
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>																
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mani Adeli Registered Number: 39,585</td><td>/Mani Adeli/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mani Adeli Registered Number: 39,585	/Mani Adeli/	Attorney								
Submitted by:	Elec. Sign.	Sign. Capacity														
Mani Adeli Registered Number: 39,585	/Mani Adeli/	Attorney														
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-fee-sheet</td><td>SPLX.P0068-usfees.xml</td></tr><tr><td></td><td>us-fee-sheet.xsl</td></tr><tr><td></td><td>us-fee-sheet.dtd</td></tr><tr><td>us-ids</td><td>SPLX.P0068-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-fee-sheet	SPLX.P0068-usfees.xml		us-fee-sheet.xsl		us-fee-sheet.dtd	us-ids	SPLX.P0068-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files															
us-fee-sheet	SPLX.P0068-usfees.xml															
	us-fee-sheet.xsl															
	us-fee-sheet.dtd															
us-ids	SPLX.P0068-usidst.xml															
	us-ids.dtd															
	us-ids.xsl															

Comments

This Information Disclosure Statement is submitted after receipt of a first Office Action on the merits but before the Final Office Action. Accordingly, a fee is required. The requisite fee is included with this electronic submission of the Information Disclosure Statement. Applicants hereby request that the one submitted fee be accepted for the second and any subsequent submission.



RECEIVED


FEE TRANSMITTAL

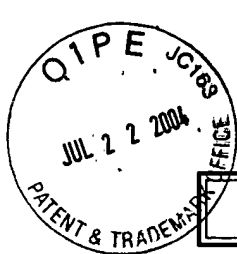
JUL 27 2004

Electronic Version v08

Stylesheet Version v08.0

TECH CENTER 2800


Title of Invention	Method and arrangement for layout and manufacture of nonmanhattan semiconductor integrated circuit using simulated euclidean wiring										
Application Number: 09/972011 											
Date: 2001-10-05											
First Named Applicant: Steven Teig											
Attorney Docket Number: SPLX.P0068											
Art Unit: 2825											
Examiner: Helen B. Rossoshek											
TOTAL FEE AUTHORIZED \$180											
Patent fees are subject to annual revisions on or about October 1st of each year.											
BASIC FILING FEE											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
Fee Description	Fee Code	Amount \$	Fee Paid \$								
Submission Of Information Disclosure Stmt Fee	1806	180	180								
AUTHORIZED BILLING INFORMATION											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
Credit account number: 7556											
Expiration Date (YYYYMMDD): 2004-08-31											
Authorized name: Mani Adeli											
Billing address: 94303											



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	Method and arrangement for layout and manufacture of nonmanhattan semiconductor integrated circuit using simulated euclidean wiring						
Application Number: 09/972011							
Confirmation Number: 5250							
First Named Applicant: Steven Teig							
Attorney Docket Number: SPLX.P0068							
Art Unit: 2825							
Examiner: Helen B. Rossoshek							
Search string: (4855253 or 5541005 or 5635736 or 5637920 or 5640327 or 5646830 or 5650653 or 5689433 or 5723908 or 5784289 or 5801385 or 5811863 or 5822214 or 5880969 or 5889329 or 5980093 or 6150193 or 6260183 or 6262487 or 6263475 or 6301686 or 6307256 or 6316838 or 6324674 or 6412097 or 6448591 or 6516455 or 20010009031 or 20030025205).pn.							
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4855253	1989-08-08	Weber			
	2	5541005	1996-07-30	Bezama et al.			
	3	5635736	1997-06-03	Funaki et al.			
	4	5637920	1997-06-10	Loo			
	5	5640327	1997-06-17	Ting			
	6	5646830	1997-07-08	Nagano			
	7	5650653	1997-07-22	Rostoker et al.			
	8	5689433	1997-11-18	Edwards			
	9	5723908	1998-03-03	Fuchida et al.			
	10	5784289	1998-07-21	Wang			
	11	5801385	1998-09-01	Endo et al.			

	12	5811863	1998-09-22	Rostoker et al.	
	13	5822214	1998-10-13	Rostoker et al.	
	14	5880969	1999-03-09	Hama et al.	
	15	5889329	1999-03-30	Rostoker et al.	
	16	5980093	1999-11-09	Jones et al.	
	17	6150193	2000-11-21	Glenn	
	18	6260183	2001-07-10	Raspopovic et al.	B1
	19	6262487	2001-07-17	Igarashi et al.	B1
	20	6263475	2001-07-17	Toyonaga et al.	B1
	21	6301686	2001-10-09	Kikuchi et al.	B1
	22	6307256	2001-10-23	Chiang et al.	B1
	23	6316838	2001-11-13	Ozawa et al.	B1
	24	6324674	2001-11-27	Andreev et al.	B2
	25	6412097	2002-06-25	Kikuchi et al.	B1
	26	6448591	2002-09-10	Juengling	B1
	27	6516455	2003-02-04	Teig et al.	B1

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20010009031	2001-07-19	Nitta et al.	A1		
	2	20030025205	2003-02-06	Shively	A1		

Signature

Examiner Name	Date